

FEATURES

- Resynchronizes data to a reference clock
- Guaranteed AC performance over temperature and voltage:
 - DC-to > 10.7Gbps data rate throughput
 - DC-to > 7GHz clock f_{MAX}
 - < 190ps Any In-to-Out t_{pd}
 - $t_r / t_f < 60ps$
- Ultra low-jitter design:
 - < 1ps_{RMS} random jitter
 - < 10ps_{PP} deterministic jitter
 - < 10ps_{PP} total jitter (clock)
- Internal 50Ω input termination
- Unique input termination and V_T pin accepts DC- and AC-coupled inputs (CML, PECL)
- Internal 50Ω output source termination
- 400mV CML output swing
- Power supply 2.5V ±5% or 3.3V ±10%
- -40°C to 85°C temperature range
- Available in a 16-pin (3mm × 3mm) MLF® package



Precision Edge®

DESCRIPTION

The SY58052U is an ultra-fast, precision, low jitter data-to-clock resynchronizer with a guaranteed maximum data and clock throughput of 10.7Gbps or 7GHz, respectively. The SY58052U is an ideal solution for backplane retiming or retiming after the data passes through long trace lengths. Serial data comes into the data input, and the CML output is synchronous to the input reference clock's rising edge.

The SY58052U differential inputs include a unique, internal termination design that allows access to the termination network through a V_T pin. This feature allows the device to easily interface to different logic standards, both AC- and DC-coupled, without external resistor-bias and termination networks. The result is a clean, stub-free, low-jitter interface solution. The differential CML output is optimized for 50Ω environments with internal 50Ω source termination and a 400mV output swing.

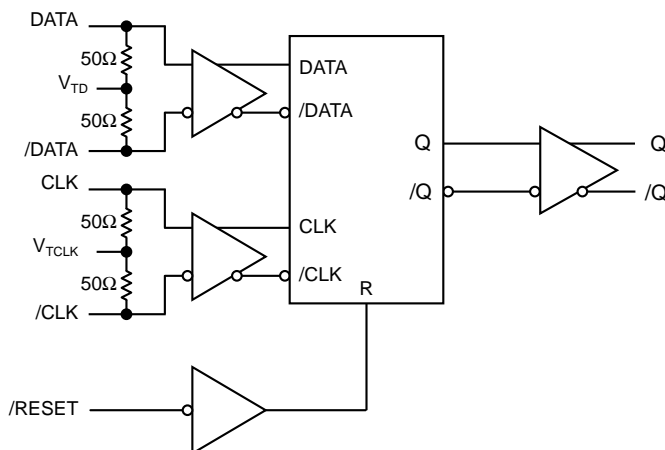
The SY58052U operates from a 2.5V or 3.3V supply and is guaranteed over the full industrial temperature range (-40°C to +85°C). The SY58052U is part of a Micrel's Precision Edge® product family.

All support documentation can be found on Micrel's web site at www.micrel.com.

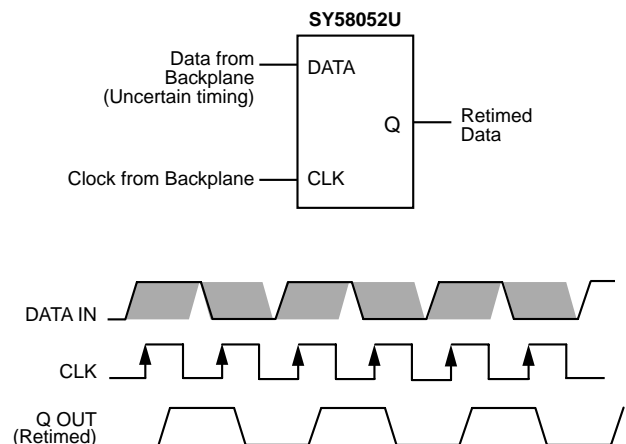
APPLICATIONS

- Data communication systems
- Serial OC-192, OC-192+FEC data-to-clock realignment
- Parallel 10Gbps for OC768
- All SONET OC-3 — OC-768 applications
- All Fibre Channel applications
- All GigE applications

FUNCTIONAL BLOCK DIAGRAM

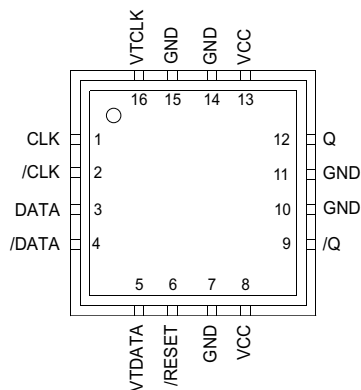


TYPICAL APPLICATION



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MicroLeadFrame and MLF are registered trademarks of Amkor Technology, Inc.

PACKAGE/ORDERING INFORMATION



16-Pin MLF® (MLF-16)

Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY58052UMI	MLF-16	Industrial	052U	Sn-Pb
SY58052UMITR ⁽²⁾	MLF-16	Industrial	052U	Sn-Pb
SY58052UMG ⁽³⁾	MLF-16	Industrial	052U with Pb-Free bar-line indicator	Pb-Free NiPdAu
SY58052UMGTR ^(2, 3)	MLF-16	Industrial	052U with Pb-Free bar-line indicator	Pb-Free NiPdAu

Notes:

1. Contact factory for die availability. Dice are guaranteed at T_A = 25°C, DC electricals only.
2. Tape and Reel.
3. Pb-Free package recommended for new designs.

PIN DESCRIPTION

Pin Number	Pin Name	Pin Function
1, 2	CLK, /CLK	Differential Input: This input pair is the clock signal that re-times the data signal at DATA, /DATA. Each pin of this pair internally terminates to the V _{TCLK} pin to 50Ω. Note that this input will default to an indeterminate state if left open. See “Input Interface Applications” section.
3, 4	DATA, /DATA	Differential Input: This input pair is the signal to be synchronized by the CLK, /CLK signal. Each pin of this pair internally terminates to the V _{TD} pin to 50Ω. Note that this input will default to an indeterminate state if left open. See “Input Interface Applications” section.
5	VTData	Input Termination Center-Tap: Each of the two inputs, DATA, /DATA terminates to this pin. The VTData pin provides a center-tap to a termination network for maximum interface flexibility. See “Input Interface Applications” section.
6	/RESET	TTL/CMOS-Compatible Input: The /RESET input asynchronously forces the Q output to a logic “0” state whenever it is active low. Possible state changes due to rising edges on CLK, /CLK are ignored until /RESET goes inactive high.
7, 10, 11, 14, 15	GND (Exposed Pad)	Ground. Exposed pad must be connected to the same potential as the GND pin.
8, 13	VCC	Positive Power Supply. Bypass with 0.1μF 0.01μF low ESR capacitors.
12, 9	Q, /Q	Differential Output: This CML output pair is the output of the flip-flop. The Data input is transferred to the Q output at the rising edge of CLK (falling edge of /CLK). See “Input Interface Applications” section.
16	VTCLK	Input Termination Center-Tap: Each of the two inputs, CLK, /CLK terminates to this pin. The VTCLK pin provides a center-tap to a termination network for maximum interface flexibility. See “Input Interface Applications” section.

TRUTH TABLES

DATA	/DATA	CLK	/CLK	/RESET	Q	/Q
X	X	X	X	0	0	1
X	X	0	1	1	Q _{N-1}	/Q _{N-1}
X	X	1	0	1	Q _{N-1}	/Q _{N-1}
0	1	⌋	⌋	1	0	1
1	0	⌋	⌋	1	1	0

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V_{CC})	-0.5V to +4.0V
Input Voltage (V_{IN})	-0.5V to V_{CC}
CML Output Voltage (V_{OUT})	$V_{CC} - 1.0V$ to $V_{CC} + 5.0V$
Termination Current ⁽³⁾	
Source or Sink Current on V_{TD} , V_{CLK}	$\pm 60mA$
Input Current	
Source or Sink Current on D, /D, CLK, /CLK	$\pm 30mA$
Lead Temperature (soldering, 20 sec.)	+260°C
Storage Temperature (T_S)	-65°C to +150°C

Operating Ratings⁽²⁾

Supply Voltage (V_{CC})	+2.375V to +2.625V
	+3.0V to +3.6V
Ambient Temperature (T_A)	-40°C to +85°C
Package Thermal Resistance ⁽⁴⁾	
MLF® (θ_{JA})	
Still-Air	61°C/W
MLF® (ψ_{JB})	
Junction-to-Board	38°C/W

DC ELECTRICAL CHARACTERISTICS⁽⁵⁾

$T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{CC}	Power Supply		2.375 3.0		2.625 3.6	V V
I_{CC}	Power Supply Current	No load, max. V_{CC} .		60	92	mA
R_{IN}	Differential Input Resistance (D, /D or CLK, /CLK)		80	100	120	Ω
V_{IH}	Input HIGH Voltage (D, /D or CLK, /CLK)	Note 6	1.2		V_{CC}	V
V_{IL}	Input LOW Voltage (D, /D or CLK, /CLK)	Note 6	0		$V_{IH} - 0.1$	V
V_{IN}	Input Voltage Swing (D, /D or CLK, /CLK)	Note 6	100			mV
V_{DIFF_IN}	Differential Input Voltage Swing D, /D or CLK, /CLK	Note 6 See Figure 2a.	200			mV
$ I_{IN} $	Input Current (IN, /IN)	Note 6 See Figure 2b.			21	mA

Notes:

1. Permanent device damage may occur if the ratings in the "Absolute Maximum Ratings" section are exceeded. This is a stress rating only and functional operation is not implied for conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Due to the limited drive capability use for input of the same package only.
4. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. ψ_{JB} uses 4-layer θ_{JA} in still-air, unless otherwise stated.
5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
6. Due to the internal termination (see "Input Structures" section) the input current depends on the applied voltages at D, /D and V_{TD} inputs, the CLK, /CLK and V_{TCLK} inputs or the S, /S and V_{TS} inputs. Do not apply a combination of voltages that causes the input current to exceed the maximum limit!

LVTTL/CMOS DC ELECTRICAL CHARACTERISTICS⁽⁷⁾

V_{CC} = 2.5V ±5% or 3.3V ±10%; T_A = -40°C to +85°C; unless otherwise noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V _{IH}	Input HIGH Voltage		2.0			V
V _{IL}	Input LOW Voltage				0.8	mV
I _{IH}	Input HIGH Current		-125		20	μA
I _{IL}	Input LOW Current				-300	μA

CML OUTPUTS DC ELECTRICAL CHARACTERISTICS⁽⁷⁾

V_{CC} = 2.5V ±5% or 3.3V ±10%; R_L = 100Ω across output pair or equivalent; T_A = -40°C to +85°C; unless otherwise noted.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V _{OH}	Output HIGH Voltage Q, /Q		V _{CC} -0.020		V _{CC}	V
V _{OUT}	Output Voltage Swing Q, /Q	See Figure 2a.	325	400	550	mV
V _{DIFF_OUT}	Differential Output Voltage Swing Q, /Q	See Figure 2b.	650	800	1000	mV
R _{OUT}	Output Source Impedance Q, /Q		40	50	60	Ω

AC ELECTRICAL CHARACTERISTICS⁽⁸⁾

V_{CC} = 2.5V ±5% or 3.3V ±10%; R_L = 100Ω across output pair or equivalent; T_A = -40°C to +85°C; unless otherwise noted.

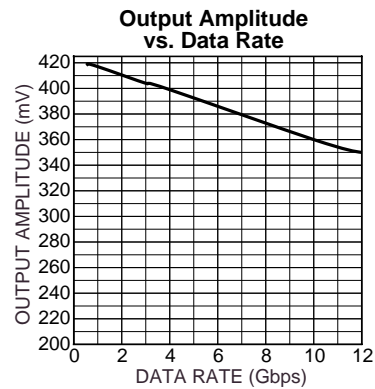
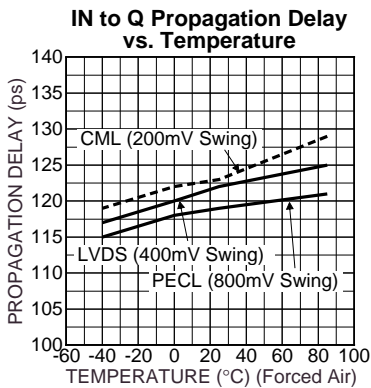
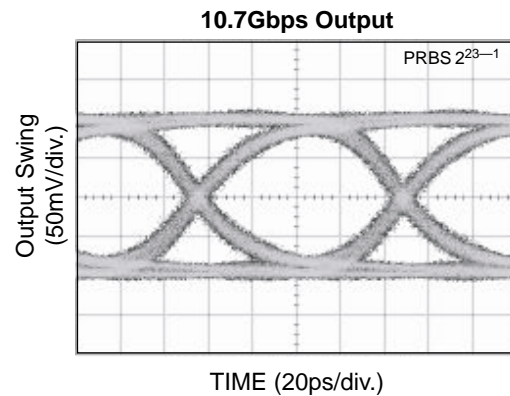
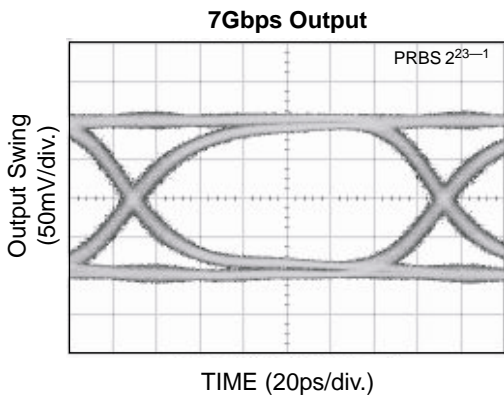
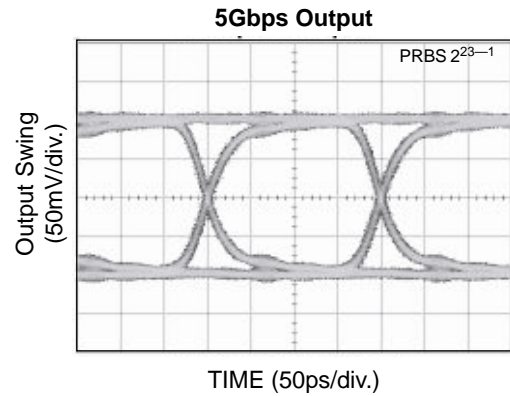
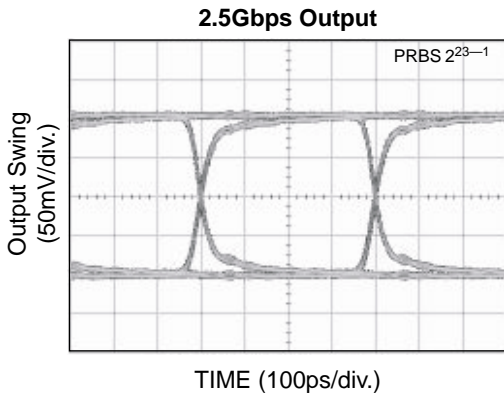
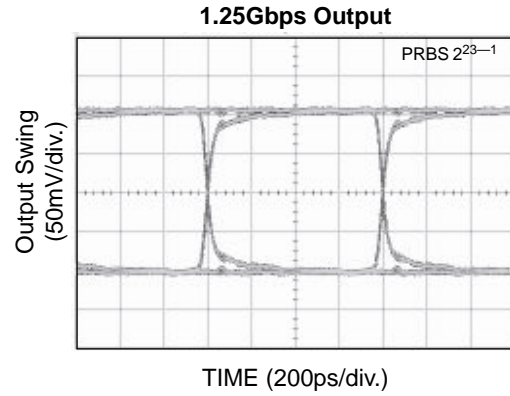
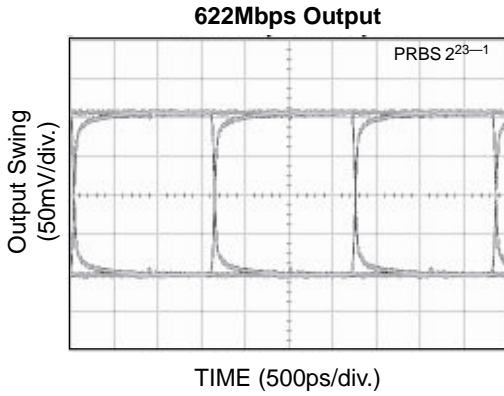
Symbol	Parameter	Condition	Min	Typ	Max	Units
f _{MAX}	Maximum Operating Frequency		10.7			GHz
t _{pd}	Propagation Delay (CLK-to-Q)		70		190	ps
t _{RESET}	Propagation Delay (RESET-to-Q)	V _{TH} = V _{CC} /2			600	ps
t _S	Set-Up Time		20			ps
t _H	Hold Time		20			ps
t _{RR}	Reset Recovery Time		500			ps
t _{JITTER}	Random Jitter (RJ)	Note 9			1	ps _{RMS}
	Deterministic Jitter (DJ)	Note 10			10	ps _{PP}
	Total Jitter (TJ)	10GHz Clock, 1× 10 ⁻¹² BER, Note 11 10GHz Data, 1× 10 ⁻¹² BER, Note 11			10 14	ps _{PP} ps _{PP}
t _r , t _f	Rise/Fall Times (20% to 80%)	At full output swing.	20	30	60	ps

Notes:

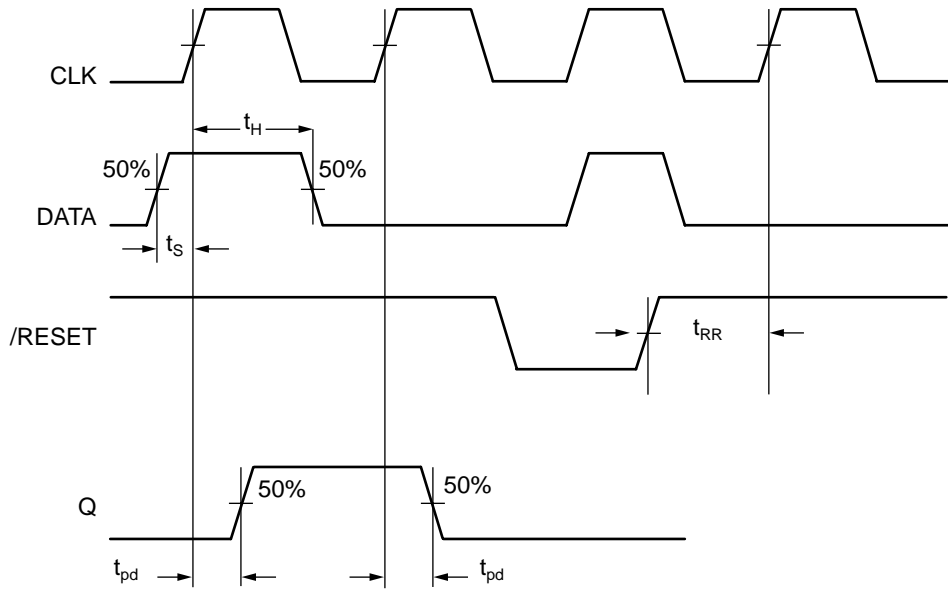
- The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
- Measured with 100mV input swing. See "Timing Diagrams" section for definition of parameters. High-frequency AC-parameters are guaranteed by design and characterization.
- RJ is measured with a K28.7 comma detect character pattern, measured at 10.7Gbps and 2.5Gbps.
- DJ is measured at 10.7Gbps and 2.5Gbps, with both K28.5 and 2²³-1 PRBS pattern
- Total jitter definition: with an ideal clock input frequency of ≤ f_{MAX}, no more than one output edge in 10¹² output edges will deviate by more than the specified peak-to-peak jitter value.

TYPICAL OPERATING CHARACTERISTICS

V_{CC} = 3.3V, GND = 0V, CLK = 400mV, D = 400mV, T_A = 25°C.



TIMING DIAGRAM



INPUT AND OUTPUT STAGE INTERNAL TERMINATION

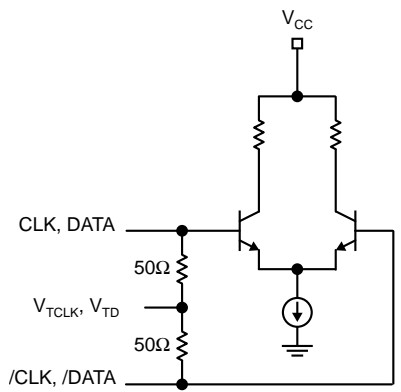


Figure 1a. Simplified Differential Input Stage

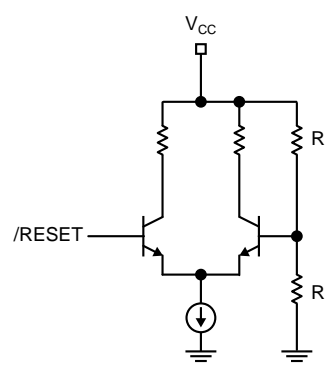


Figure 1b. Simplified TTL/CMOS Input

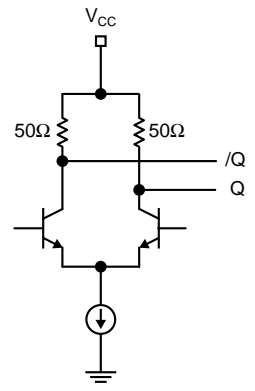


Figure 1c. Simplified Differential Output Stage

OPERATING CHARACTERISTICS

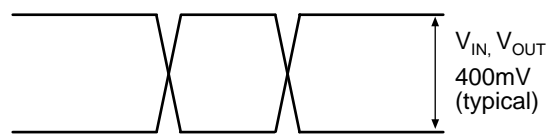


Figure 2a. Single-Ended Swing

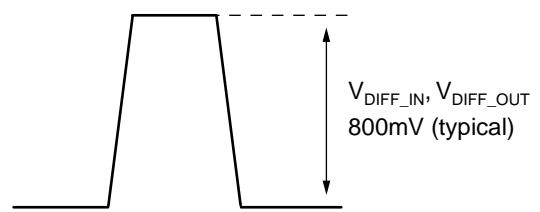


Figure 2b. Differential Swing

Definition of Single-Ended and Differential Swings

INPUT INTERFACE APPLICATIONS

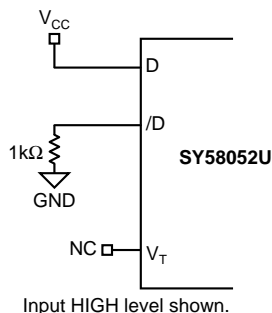


Figure 3a. Static Input Level

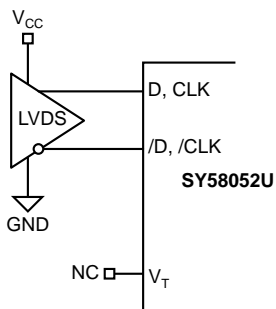


Figure 3b. LVDS Interface (DC-Coupled)

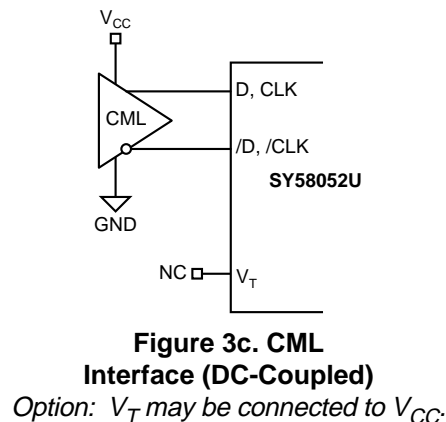


Figure 3c. CML Interface (DC-Coupled)
Option: V_T may be connected to V_{CC} .

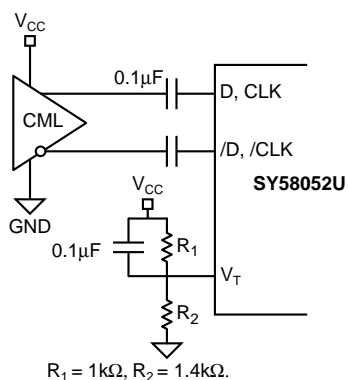


Figure 3d. CML Interface (AC-Coupled)

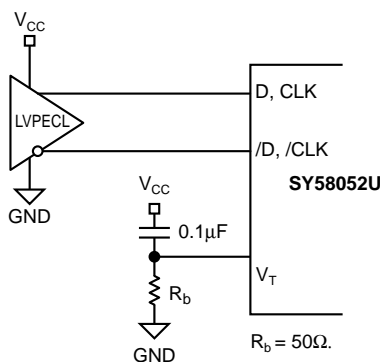


Figure 3e. LVPECL Interface (DC-Coupled)

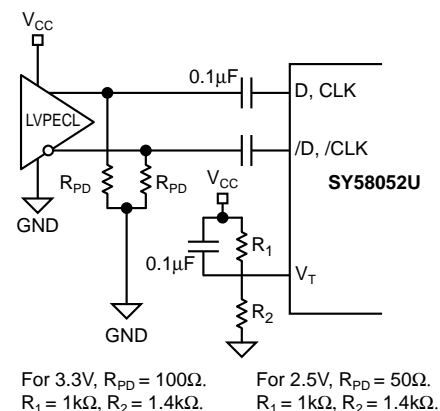
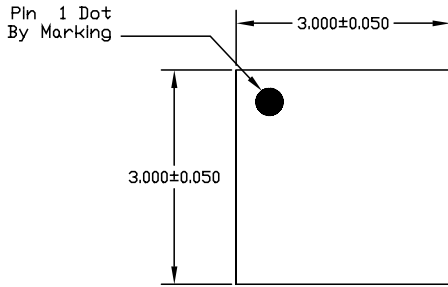


Figure 3f. LVPECL Interface (AC-Coupled)

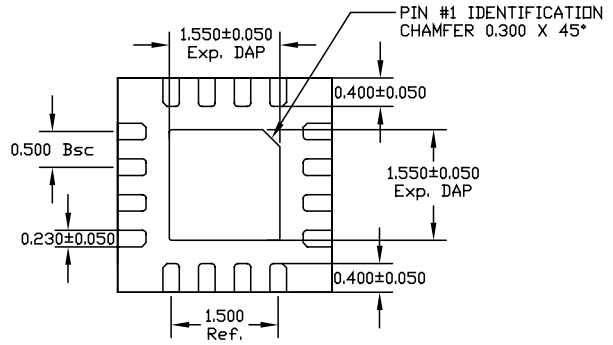
RELATED PRODUCT AND SUPPORT DOCUMENTATION

Part Number	Function	Data Sheet Link
SY58016L	3.3V 10Gbps Differential CML Line Driver/ Receiver with Internal Termination	www.micrel.com/product-info/products/sy58016l.shtml
SY58051U	10.7Gbps AnyGate® with Internal Input and Output Termination	www.micrel.com/product-info/products/sy58051u.shtml
	MLF® Application Note	www.amkor.com/products/notes_papers/MLF_AppNote_0902.pdf
HBW Solutions	New Products and Applications	www.micrel.com/product-info/products/solutions.shtml

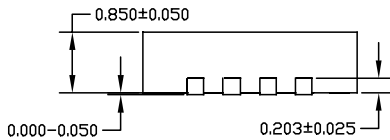
16-PIN MicroLeadFrame® (MLF-16)



TOP VIEW



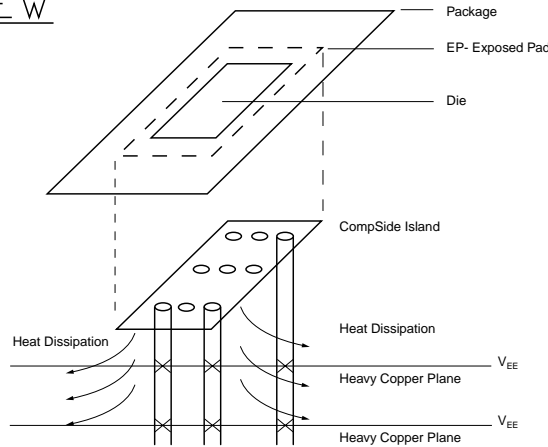
BOTTOM VIEW



SIDE VIEW

NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MAX. PACKAGE WARPAGE IS 0.05 mm.
3. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.



**PCB Thermal Consideration for 16-Pin MLF® Package
(Always solder, or equivalent, the exposed pad to the PCB)**

Package Notes:

1. Package meets Level 2 qualification.
2. All parts dry-packaged before shipment.
3. Exposed pads must be soldered to a ground for proper thermal management.

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